

Product End-of-Life Disassembly Instructions

Product Name / Model: DT Research Rugged Convertible Laptop / LT320

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of DT Research products to remove components and materials requiring selective treatment, as defined by EU Directive 2012/19/EU of the European Parliament and of the Council of 4 July 2012 on waste electrical and electronic equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in
Printed Circuit Boards Assemblies (PCBA)	With a surface greater than 10 sq cm	4
Mass storage device	Permanently soldered to PCBA	0
Batteries	All types including standard alkaline and lithium coin or button style	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps,	0
LCD Display	a surface greater than 100 sq cm includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in		0
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including PCBs or PCBAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids	Include the cartridges, print heads, tubes, vent chambers,	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Philips screwdriver	
Description #2 Slotted screwdriver	
Description #3 Hex screwdriver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

- (1) Dismantle system.
- (2) Dismantle enclosure B.
- (3) Dismantle enclosure C.
- (4) Dismantle enclosure D.
- (5) Dismantle enclosure A.
- (6) Dismantle PCBA.

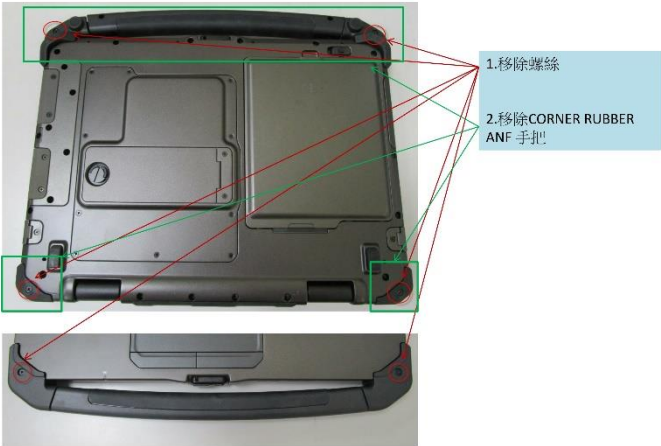
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

- (1) Dismantle system

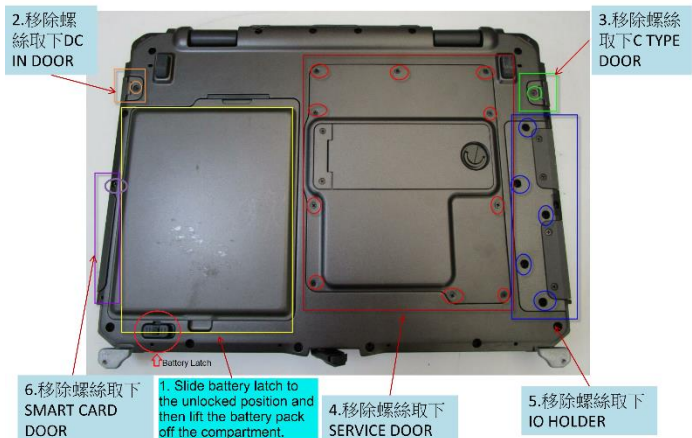
LT320 拆解步驟-系統(1)



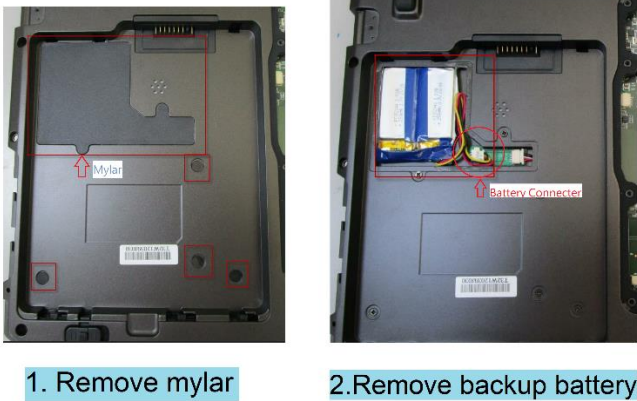
LT320 拆解步驟-系統(2)



LT320 拆解步驟-系統(3)



LT320 拆解步驟-系統(4)



Replacing the battery pack by hand:

- 1. Slide battery latch to the unlocked position
- 2. Lift the battery pack off the comartment

Replacing the backup battery by hand:

- 1. Remove mylar
- 2. Remove battery connector and take off the backup battery.

LT320 拆解步驟-系統(5)



1. 移除螺絲取下C PART

LT320 拆解步驟-系統(6)



2. 移除MB CABLE/FFC CABLE

LT320 拆解步驟-系統(7)

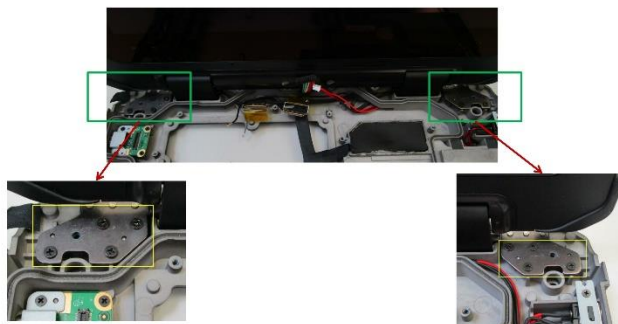


1. 移除螺絲，取下MB

2. 移除MB板下CABLE



LT320 拆解步驟-系統(8)



1. 移除螺絲，取下B PART

(2) Dismantle enclosure B

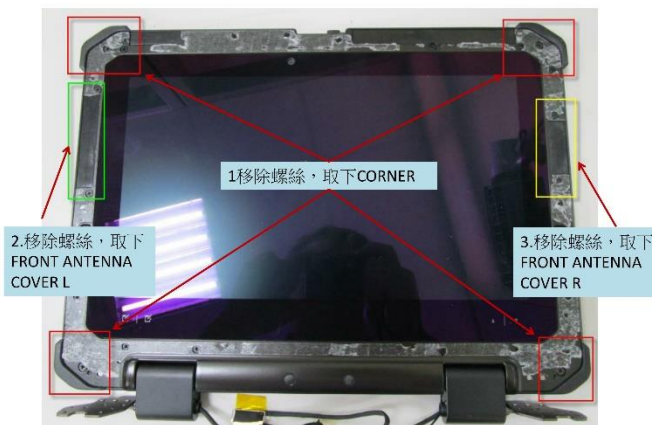
LT320 拆解步驟-B PART(1)



1. 移除2個MYLAR

2. 移除RUBBER

LT320 拆解步驟-B PART(2)

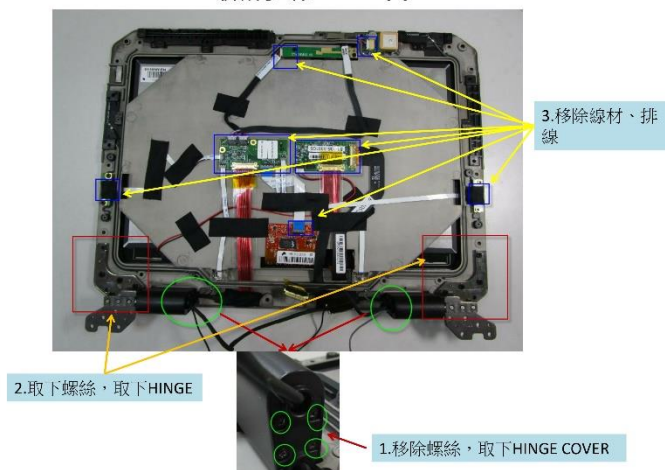


1. 移除螺絲，取下CORNER

2. 移除螺絲，取下FRONT ANTENNA COVER L

3. 移除螺絲，取下FRONT ANTENNA COVER R

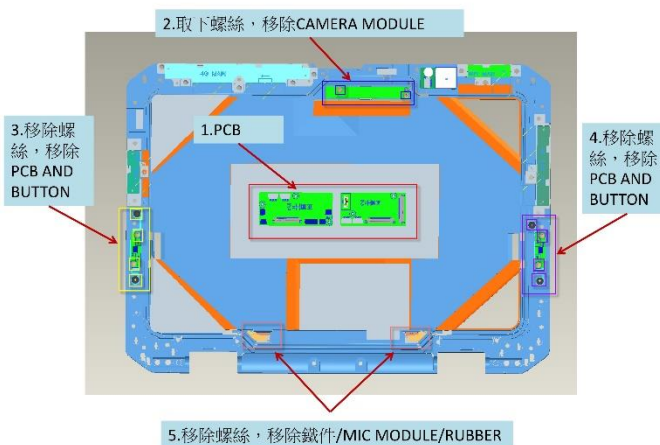
LT320 拆解步驟-B PART(3)



2. 取下螺絲，取下HINGE

1. 移除螺絲，取下HINGE COVER

LT320 拆解步驟-B PART(4)



2. 取下螺絲，移除CAMERA MODULE

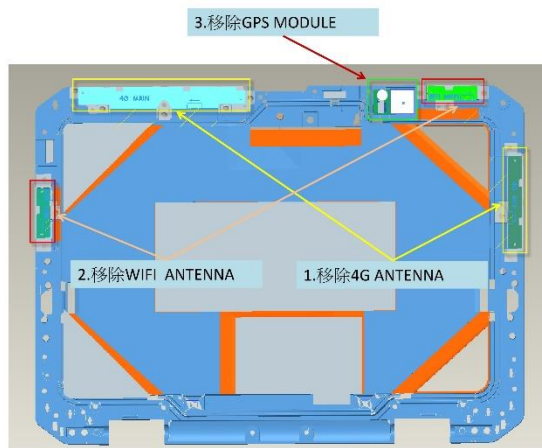
1. PCB

3. 移除螺絲，移除PCB AND BUTTON

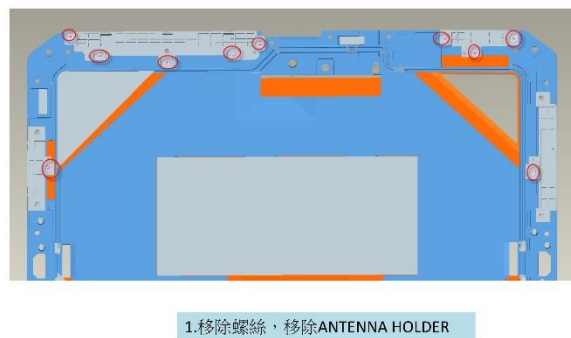
4. 移除螺絲，移除PCB AND BUTTON

5. 移除螺絲，移除鐵件/MIC MODULE/RUBBER

LT320 拆解步驟-B PART(5)

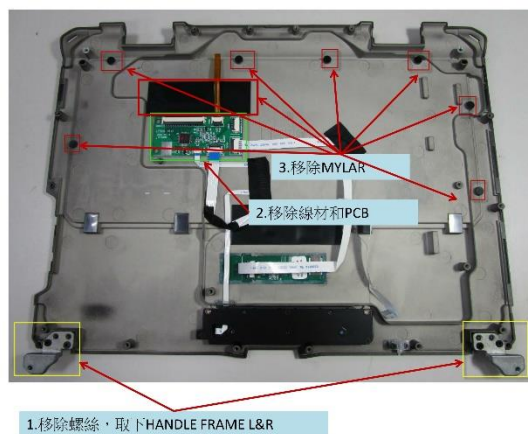


LT320 拆解步驟-B PART(6)

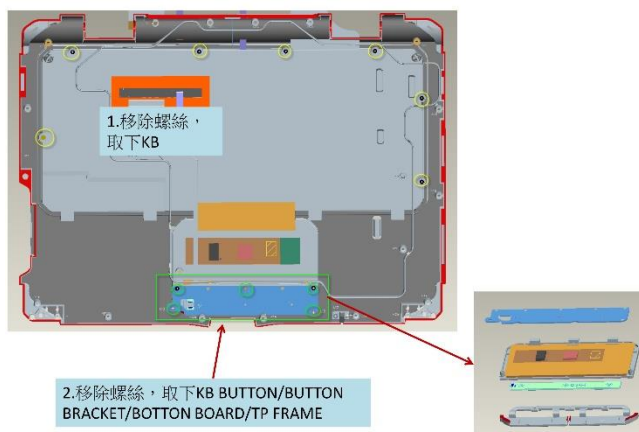


(3) Dismantle enclosure C

LT320 拆解步驟-C PART(1)

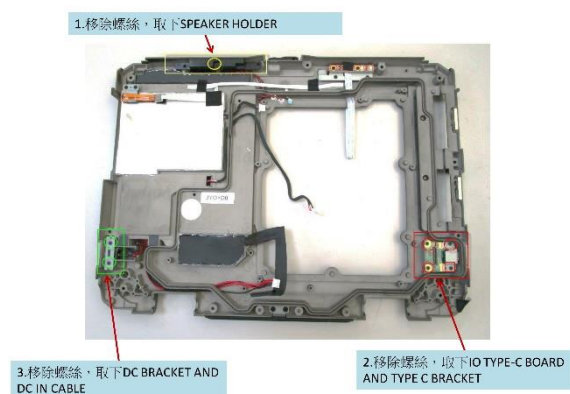


LT320 拆解步驟-C PART(2)

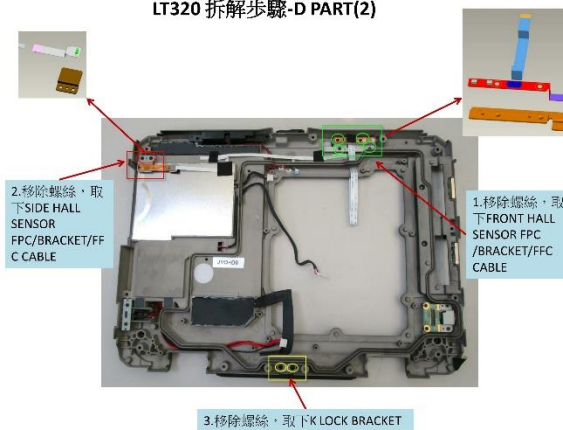


(4) Dismantle enclosure D

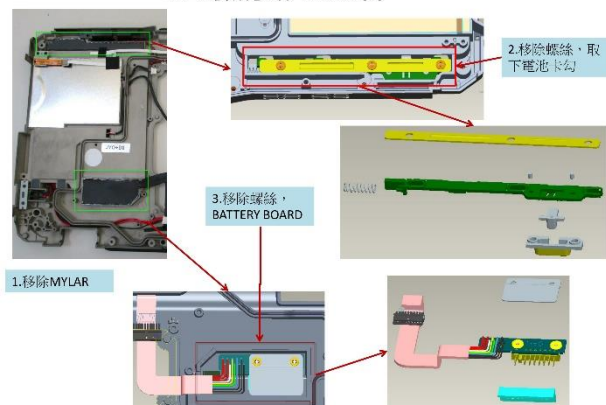
LT320 拆解步驟-D PART(1)



LT320 拆解步驟-D PART(2)



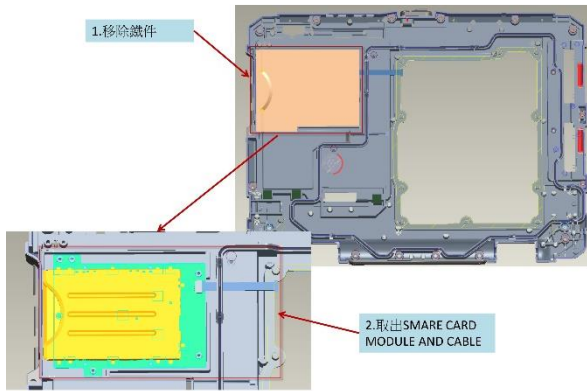
LT320 拆解步驟-D PART(3)



LT320 拆解步驟-D PART(4)



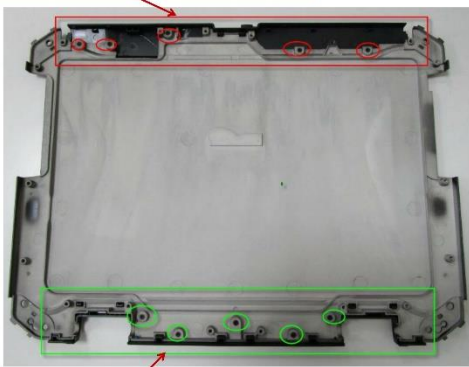
LT320 拆解步驟-D PART(5)



(5) Dismantle enclosure A

LT320 拆解步驟-A PART(1)

1. 移除螺絲，取下FRONT ANTENNA COVER T



2. 移除螺絲，取下HINGE COVER T

(6) Dismantle PCBA

LT320 拆解步驟-MB PART

2. 移除螺絲，取下鐵件和I4G MODULE



1. 取下SODIMM

2. 移除螺絲，取下SSD



4. 移除螺絲，取下THERMAL MODULE